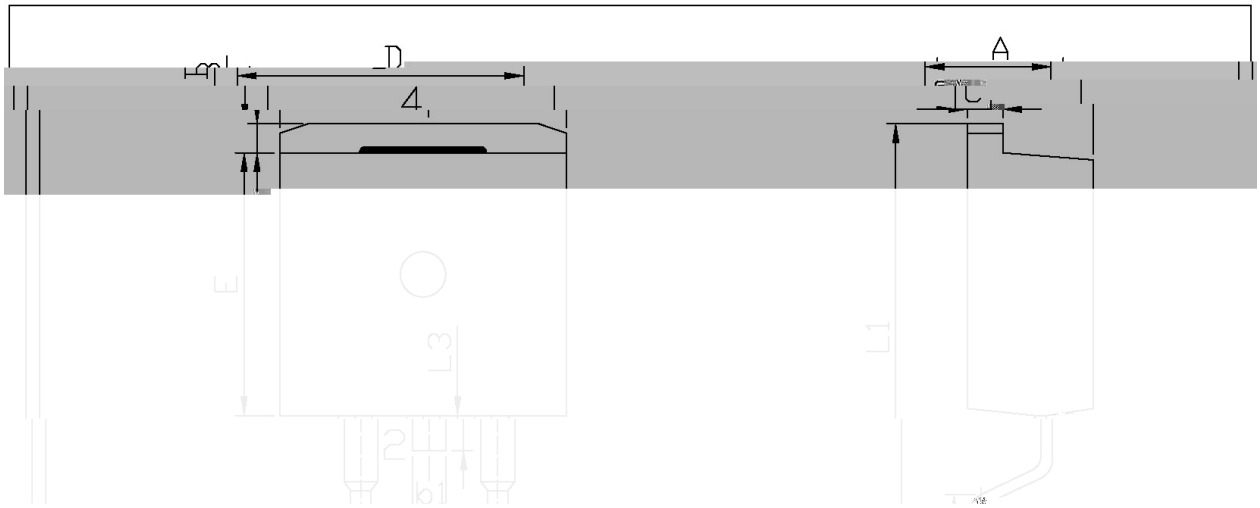
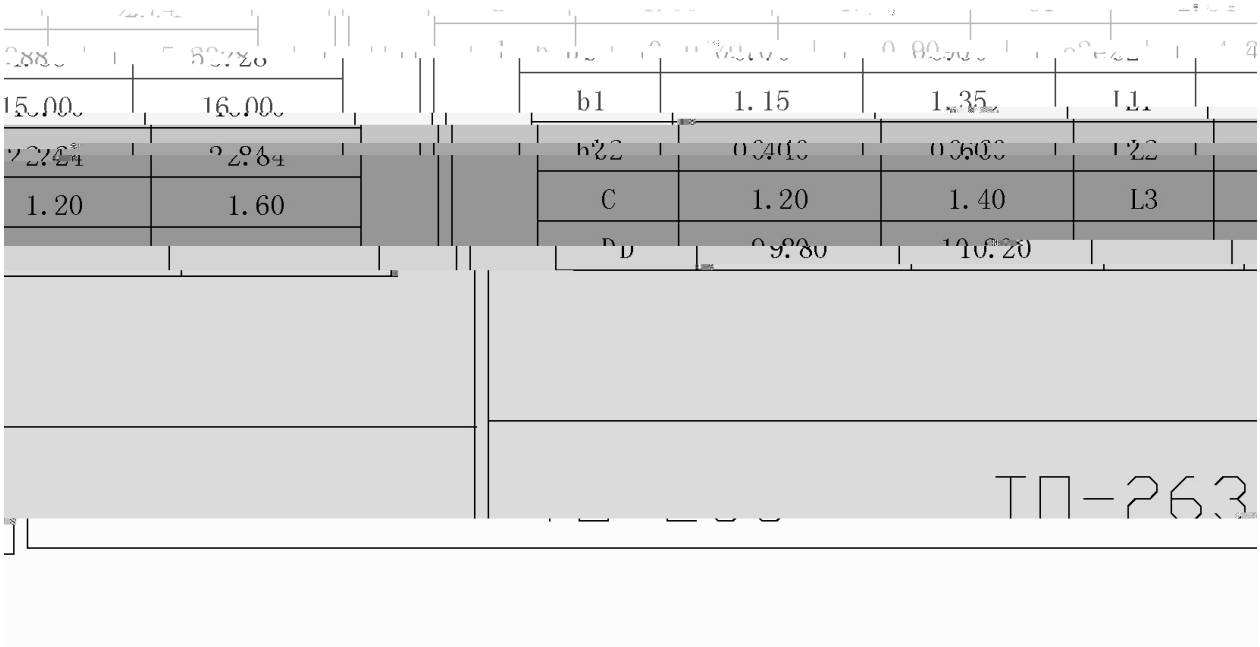
v ̈Ω Parameter	ϒ N Symbol	̈Ω Ö Rating	D Ɥ Unit
Collector to Base Voltage	V_{CBO}	100	V
Collector to Emitter Voltage	V_{CEO}	100	V
Emitter to Base Voltage	V_{EBO}	5	V
Collector Current - Continuous	I_C	6	A
Peak Collector Current	I_{CP}	10	A
Base Current - Continuous	I_B	2	A
Collector Power Dissipation	P_C	2	W
Collector Power Dissipation	P_C (T_c=25)	65	W
Junction Temperature	T_j	150	
Storage Temperature Range	T_{sag}	-55 150	

v ̈Ω Parameter	ϒ N Symbol	⊥ ;ϯ ϯ Test Conditions	ω ŋ Ö Min	Ɛ ʒ Ö Typ	ω ᶻ Ö Max	D Ɥ Unit
Collector to Emitter Breakdown V						

TIP41CB
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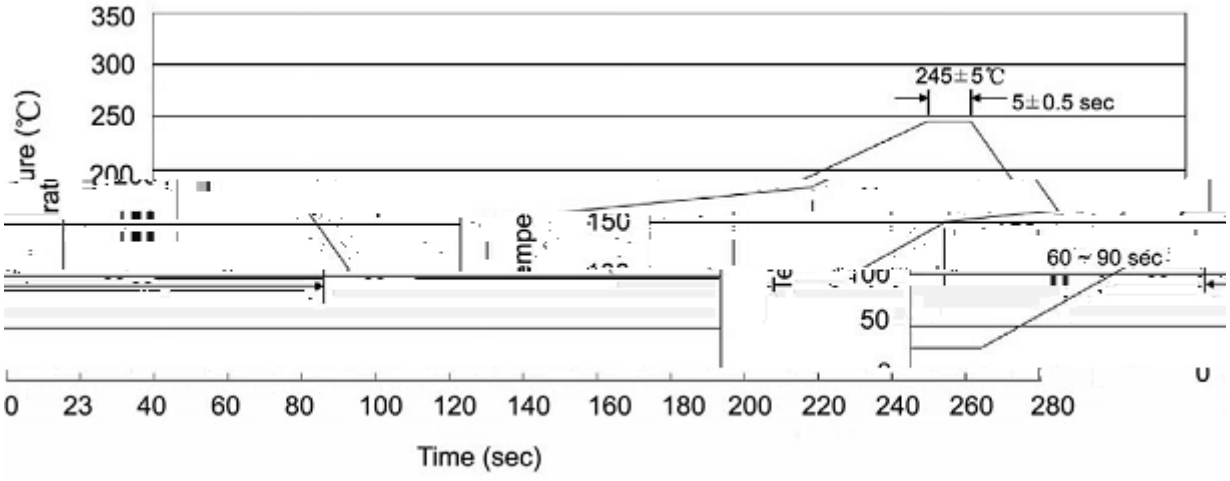
/ Package Dimensions





• ÞZVAkÞZož

( ) / Temperature Profile for Dip Soldering(Pb-Free)



ب ˝ χ

1 Ĺ ♬ □ ỷ 25 Ḱ 150 ł ı ˋH ڑ 60 Ḱ 90sec;

2 Š Ө □ ỷ 245 ° 5 ł ı ˋH ڑ ˋY ㅅ ㎞ 5 ° 0.5sec;

3 ì ˙ ㅅ ˛ ɔ ଌ ỷ ㎞ 2 Ḱ 10 ł /sec.

Note:

1.Preheating:25~150 ł , Time:60~90sec.

2.Peak Temp.:245 ° 5 ł , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ł /sec.

/ Resistance to Soldering Heat Test Conditions

□ ỷ χ 260 ° 5 ł ˋH ڑ χ 10 ° 1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

ɔ ` ㅛ Ł / REEL

Package Type	Units					Dimension		(unit mm³)
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
TO-263	800	1	800	5	4,000	13 ×24	360×360×50	385×257×392

˛ ㄱ ㅛ Ł / TUBE

Package Type	Units					Dimension		(unit mm³)
	Units/Tube /	Tubes/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Tube	Inner Box	Outer Box
TO-263	50	20	1,000	5	5,000	532×33×7.0	555×164×50	575×290×180

/ Notices